

20V N-Channel Enhancement Mode MOSFET

Description

The CP80N02QR uses advanced trench technology and design to provide excellent $R_{DS(ON)}$. This device is ideal for high-frequency switching and synchronous rectification.

General Features

- ◆ $V_{DS} = 20V$, $I_D = 80A$
 $R_{DS(ON)} = 3.6m\Omega$ (typical) @ $V_{GS} = 4.5V$
 $R_{DS(ON)} = 4.7 m\Omega$ (typical) @ $V_{GS} = 2.5V$
- ◆ Excellent gate charge x $R_{DS(ON)}$ product(FOM)
- ◆ Very low on-resistance $R_{DS(ON)}$
- ◆ 150 °C operating temperature
- ◆ Pb-free lead plating
- ◆ 100% UIS tested

Application

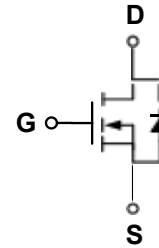
- ◆ DC/DC Converter
- ◆ Ideal for high-frequency switching and synchronous rectification

Package

- ◆ PDFN3X3-8L



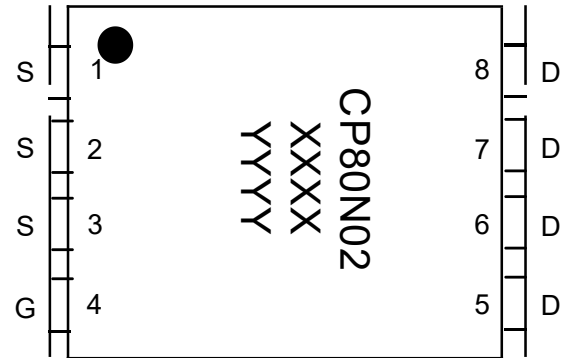
Schematic diagram



Marking and pin assignment

PDFN3X3-8L

(Top View)



XXXX—Wafer Information

YYYY—Quality Code

Ordering Information

Part Number	Storage Temperature	Package	Devices Per Reel
CP80N02QR-G	-55°C to +150°C	PDFN3X3-8L	5000

Absolute Maximum Ratings (TA=25°C unless otherwise noted)

parameter	symbol	limit	unit
Drain-source voltage	V_{DS}	20	V
Gate-source voltage	V_{GS}	±12	V
Drain Current-Continuous (Silicon Limited)	I_D	80	A
Pulsed Drain Current (Package Limited)	I_{DM}	320	A
Single pulse avalanche energy	E_{AS}	125	mJ
Maximum power dissipation	P_D	60	W
Operating junction Temperature range	T_j	-55—150	°C

Electrical Characteristics (TA=25°C unless otherwise noted)

Parameter	Symbol	Condition	Min	Typ	Max	Unit
OFF Characteristics						
Drain-source breakdown voltage	BV _{DSS}	V _{GS} =0V, I _D =250μA	20	-	-	V
Zero gate voltage drain current	I _{DSS}	V _{DS} =20V, V _{GS} =0V	-	-	1	μA
Gate-body leakage	I _{GSS}	V _{DS} =0V, V _{GS} =±12V	-	-	±100	nA
ON Characteristics						
Gate threshold voltage	V _{GS(th)}	V _{DS} =V _{GS} , I _D =250μA	0.4	0.6	1.0	V
Drain-source on-state resistance	R _{DS(ON)}	V _{GS} =4.5V, I _D =10A	-	3.6	4.5	mΩ
		V _{GS} =2.5V, I _D =10A	-	4.7	6.5	
Forward transconductance	g _{fs}	V _{DS} =5V, I _D =5A	-	35	-	S
Dynamic Characteristics						
Input capacitance	C _{ISS}	V _{DS} =10V ,V _{GS} =0V f=1.0MHz	-	2344	-	pF
Output capacitance	C _{OSS}		-	425	-	
Reverse transfer capacitance	C _{RSS}		-	407	-	
Switching Characteristics						
Turn-on delay time	t _{D(ON)}	V _{DS} =10V I _D =2.8A V _{GEN} =4.5V R _L =10ohm R _{GEN} =60ohm	-	20	-	ns
Rise time	t _r		-	31	-	
Turn-off delay time	t _{D(OFF)}		-	40	-	
Fall time	t _f		-	21	-	
Total gate charge	Q _g	V _{DS} =10V,I _D =3A V _{GS} =5V	-	36.3	-	nC
Gate-source charge	Q _{gs}		-	3.6	-	
Gate-drain charge	Q _{gd}		-	9.7	-	

Thermal Characteristics

Thermal Resistance junction-to ambient	$R_{th JA}$	62	$^{\circ}C/W$
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Typical Performance Characteristics

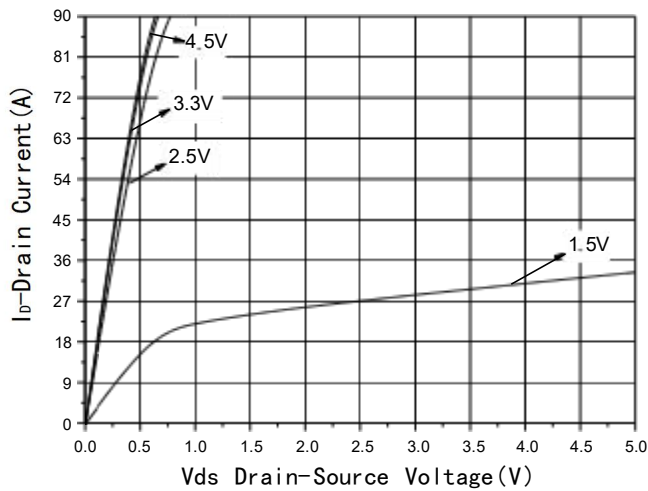


Fig1 Output Characteristics

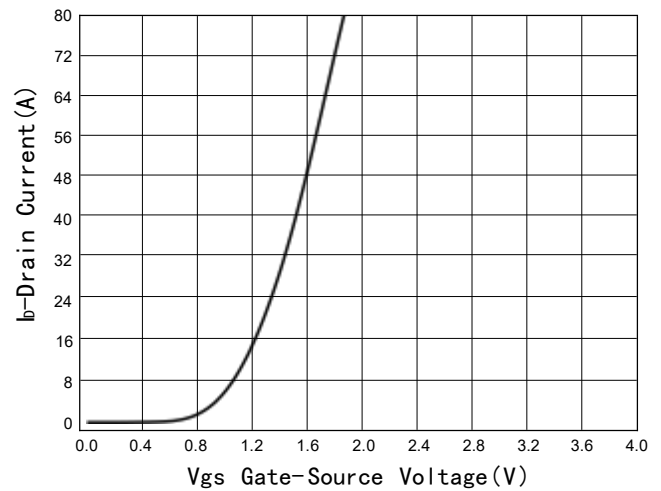


Fig2 Transfer Characteristics

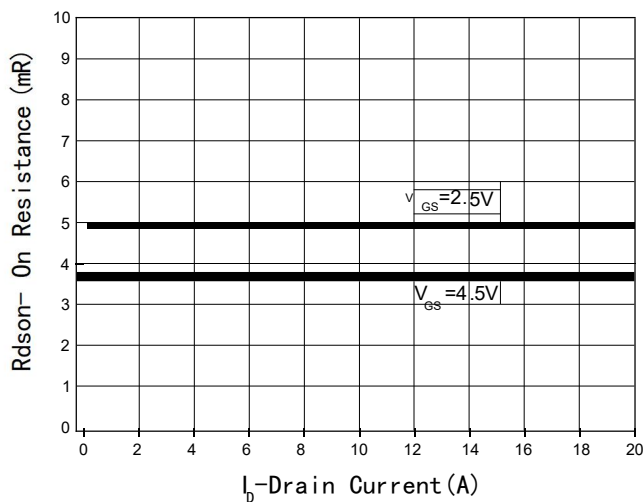


Fig3 $R_{DS(on)}$ -Drain current

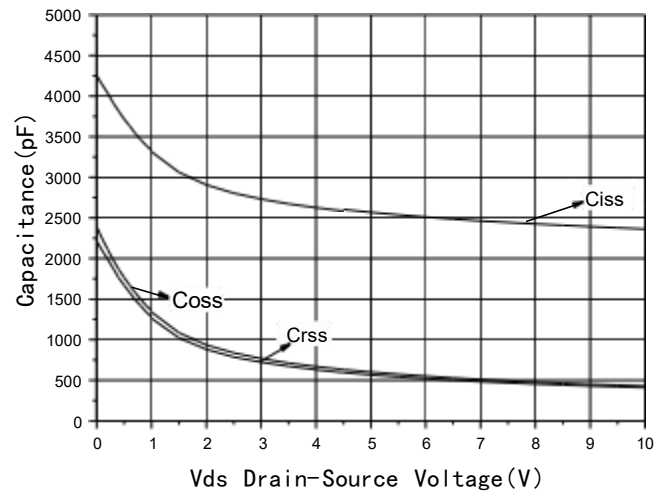


Fig4 Capacitance vs V_{DS}

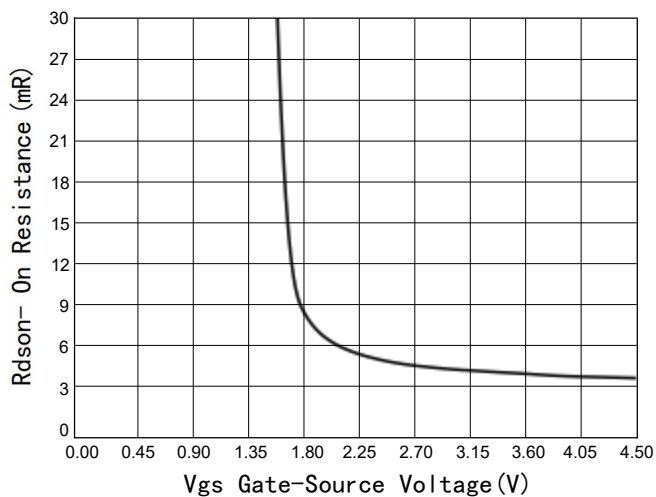


Fig5 $R_{DS(on)}$ -Gate Drain voltage

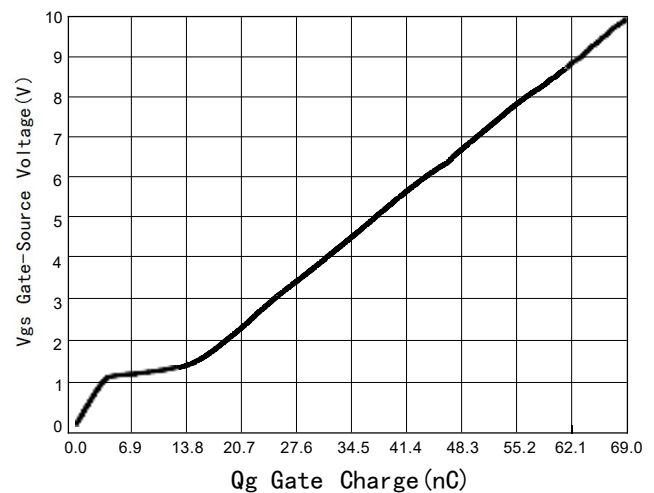
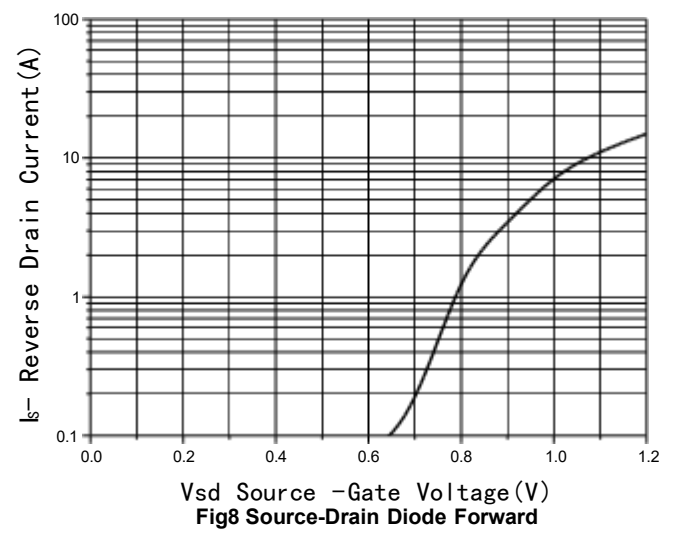
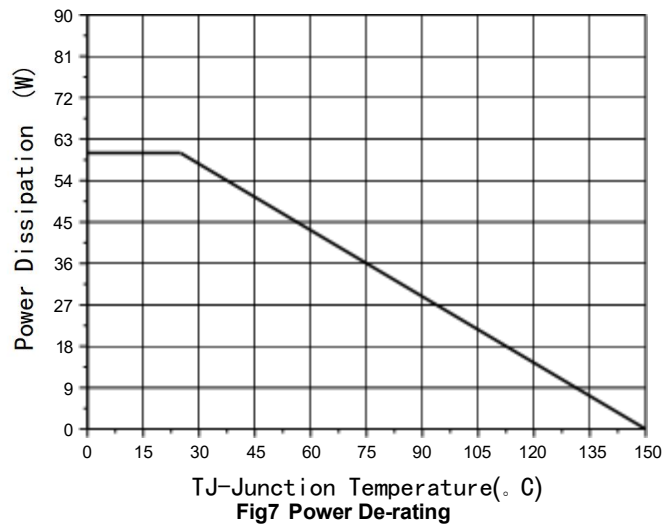


Fig6 Gate Charge



Package Information

 PDFN3*3-8L

